

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings^(†)

Vcc.....	7.0V
All inputs and outputs w.r.t. Vss	-0.6V to Vcc + 1.0V
Storage temperature	-65°C to +150°C
Ambient temperature with power applied.....	-40°C to +125°C
Soldering temperature of leads (10 seconds)	+300°C
ESD protection on all pins	4 kV

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

1.1 AC Test Conditions

- AC Waveform:
- VLO = 2.0V
 - VHI = Vcc - 0.2V (Note 1)
 - VHI = 4.0V for (Note 2)

Timing Measurement Reference Level

Input	0.5 Vcc
Output	0.5 Vcc

- Note 1:** For Vcc ≤ 4.0V
- 2:** For Vcc > 4.0V

TABLE 1-1: DC CHARACTERISTICS

DC CHARACTERISTICS Applicable over recommended operating ranges shown below unless otherwise noted: V _{CC} = +2.5V to +6.0V Commercial (C): T _A = 0°C to +70°C Industrial (I): T _A = -40°C to +85°C					
Parameter	Symbol	Min.	Max.	Units	Conditions
High-level input voltage	V _{IH1}	2.0	V _{CC} + 1	V	V _{CC} ≥ 2.7V
	V _{IH2}	0.7 V _{CC}	V _{CC} + 1	V	V _{CC} < 2.7V
Low-level input voltage	V _{IL1}	-0.3	0.8	V	V _{CC} ≥ 2.7V
	V _{IL2}	-0.3	0.2 V _{CC}	V	V _{CC} < 2.7V
Low-level output voltage	V _{OL1}	—	0.4	V	I _{OL} = 2.1 mA; V _{CC} = 4.5V
	V _{OL2}	—	0.2	V	I _{OL} = 100 μA; V _{CC} = V _{CC} Min.
High-level output voltage	V _{OH1}	2.4	—	V	I _{OH} = -400 μA; V _{CC} = 4.5V
	V _{OH2}	V _{CC} -0.2	—	V	I _{OH} = -100 μA; V _{CC} = V _{CC} Min.
Input leakage current	I _{LI}	-10	10	μA	V _{IN} = 0.1V to V _{CC}
Output leakage current	I _{LO}	-10	10	μA	V _{OUT} = 0.1V to V _{CC}
Pin capacitance (all inputs/outputs)	C _{INT}	—	7	pF	(Note 1) T _A = +25°C, F _{CLK} = 1 MHz
Operating current	I _{CC} write	—	3	mA	V _{CC} = 5.5V
	I _{CC} read	—	1 500	mA μA	F _{CLK} = 3 MHz; V _{CC} = 5.5V F _{CLK} = 1 MHz; V _{CC} = 3.0V
Standby current	I _{CCS}	—	100	μA	CLK = CS = 0V; V _{CC} = 5.5V
			30	μA	CLK = CS = 0V; V _{CC} = 3.0V DI = PE = V _{SS} ORG = V _{SS} or V _{CC}

Note 1: This parameter is periodically sampled and not 100% tested.

TABLE 1-2: AC CHARACTERISTICS

AC CHARACTERISTICS Applicable over recommended operating ranges shown below unless otherwise noted: $V_{CC} = +2.5V$ to $+6.0V$ Commercial (C): $T_A = 0^{\circ}C$ to $+70^{\circ}C$ Industrial (I): $T_A = -40^{\circ}C$ to $+85^{\circ}C$					
Parameter	Symbol	Min.	Max.	Units	Conditions
Clock frequency	FCLK	—	3 2	MHz MHz	$4.5V \leq V_{CC} \leq 6.0V$ $2.5V \leq V_{CC} < 4.5V$
Clock high time	TCKH	200 300	—	ns ns	$4.5V \leq V_{CC} \leq 6.0V$ $2.5V \leq V_{CC} < 4.5V$
Clock low time	TCKL	100 200	—	ns ns	$4.5V \geq V_{CC} \leq 6.0V$ $2.5V \leq V_{CC} < 4.5V$
Chip select setup time	Tcss	50 100	—	ns ns	$4.5V \leq V_{CC} \leq 6.0V$, Relative to CLK $2.5V \leq V_{CC} < 4.5V$, Relative to CLK
Chip select hold time	Tcsh	0	—	ns	—
Chip select low time	TCSL	250	—	ns	Relative to CLK
Data input setup time	Tdis	50 100	—	ns ns	$4.5V \leq V_{CC} \leq 6.0V$, Relative to CLK $2.5V \leq V_{CC} < 4.5V$, Relative to CLK
Data input hold time	Tdih	50 100	—	ns ns	$4.5V \leq V_{CC} \leq 6.0V$, Relative to CLK $2.5V \leq V_{CC} < 4.5V$, Relative to CLK
Data output delay time	TPD	—	100 250	ns ns	$4.5V \leq V_{CC} \leq 6.0V$, $C_L = 100$ pF $2.5V \leq V_{CC} < 4.5V$, $C_L = 100$ pF
Data output disable time	TCZ	—	100 500	ns ns	$4.5V \leq V_{CC} \leq 6.0V$ $2.5V \leq V_{CC} < 4.5V$ (Note 1)
Status valid time	Tsv	—	200 300	ns ns	$4.5V \geq V_{CC} \leq 6.0V$, $C_L = 100$ pF $2.5V \leq V_{CC} < 4.5V$, $C_L = 100$ pF
Program cycle time	TWC	—	5	ms	Erase/Write mode
	TEC	—	15	ms	ERAL mode
	TWL	—	30	ms	WRAL mode
Endurance	—	1M	—	cycles	$25^{\circ}C$, $V_{CC} = 5.0V$, Block mode (Note 2)

Note 1: This parameter is periodically sampled and not 100% tested.

2: This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which can be obtained from Microchip's web site at www.microchip.com.

TABLE 1-3: INSTRUCTION SET FOR 93LC76: ORG=1 (1X16 ORGANIZATION)

Instruction	SB	Opcode	Address	Data In	Data Out	Req. CLK Cycles
READ	1	10	X A8 A7 A6 A5 A4 A3 A2 A1 A0	—	D15 - D0	29
EWEN	1	00	1 1 X X X X X X X X	—	High-Z	13
ERASE	1	11	X A8 A7 A6 A5 A4 A3 A2 A1 A0	—	(RDY/BSY)	13
ERAL	1	00	1 0 X X X X X X X X	—	(RDY/BSY)	13
WRITE	1	01	X A8 A7 A6 A5 A4 A3 A2 A1 A0	D15 - D0	(RDY/BSY)	29
WRAL	1	00	0 1 X X X X X X X X	D15 - D0	(RDY/BSY)	29
EWDS	1	00	0 0 X X X X X X X X	—	High-Z	13

TABLE 1-4: INSTRUCTION SET FOR 93LC76: ORG=0 (X8 ORGANIZATION)

Instruction	SB	Opcode	Address	Data In	Data Out	Req. CLK Cycles
READ	1	10	X A9 A8 A7 A6 A5 A4 A3 A2 A1 A0	—	D7 - D0	22
EWEN	1	00	1 1 X X X X X X X X	—	High-Z	14
ERASE	1	11	X A9 A8 A7 A6 A5 A4 A3 A2 A1 A0	—	(RDY/BSY)	14
ERAL	1	00	1 0 X X X X X X X X	—	(RDY/BSY)	14
WRITE	1	01	X A9 A8 A7 A6 A5 A4 A3 A2 A1 A0	D7 - D0	(RDY/BSY)	22
WRAL	1	00	0 1 X X X X X X X X	D7 - D0	(RDY/BSY)	22
EWDS	1	00	0 0 X X X X X X X X	—	High-Z	14

TABLE 1-5: INSTRUCTION SET FOR 93LC86: ORG=1 (X16 ORGANIZATION)

Instruction	SB	Opcode	Address	Data In	Data Out	Req. CLK Cycles
READ	1	10	A9 A8 A7 A6 A5 A4 A3 A2 A1 A0	—	D15 - D0	29
EWEN	1	00	1 1 X X X X X X X X	—	High-Z	13
ERASE	1	11	A9 A8 A7 A6 A5 A4 A3 A2 A1 A0	—	(RDY/BSY)	13
ERAL	1	00	1 0 X X X X X X X X	—	(RDY/BSY)	13
WRITE	1	01	A9 A8 A7 A6 A5 A4 A3 A2 A1 A0	D15 - D0	(RDY/BSY)	29
WRAL	1	00	0 1 X X X X X X X X	D15 - D0	(RDY/BSY)	29
EWDS	1	00	0 0 X X X X X X X X	—	High-Z	13

TABLE 1-6: INSTRUCTION SET FOR 93LC86: ORG=0 (X8 ORGANIZATION)

Instruction	SB	Opcode	Address	Data In	Data Out	Req. CLK Cycles
READ	1	10	A10 A9 A8 A7 A6 A5 A4 A3 A2 A1 A0	—	D7 - D0	22
EWEN	1	00	1 1 X X X X X X X X	—	High-Z	14
ERASE	1	11	A10 A9 A8 A7 A6 A5 A4 A3 A2 A1 A0	—	(RDY/BSY)	14
ERAL	1	00	1 0 X X X X X X X X	—	(RDY/BSY)	14
WRITE	1	01	A10 A9 A8 A7 A6 A5 A4 A3 A2 A1 A0	D7 - D0	(RDY/BSY)	22
WRAL	1	00	0 1 X X X X X X X X	D7 - D0	(RDY/BSY)	22
EWDS	1	00	0 0 X X X X X X X X	—	High-Z	14

2.0 PRINCIPLES OF OPERATION

When the ORG pin is connected to Vcc, the x16 organization is selected. When it is connected to ground, the x8 organization is selected. Instructions, addresses and write data are clocked into the DI pin on the rising edge of the clock (CLK). The DO pin is normally held in a high-Z state except when reading data from the device, or when checking the Ready/Busy status during a programming operation. The Ready/Busy status can be verified during an erase/write operation by polling the DO pin; DO low indicates that programming is still in progress, while DO high indicates the device is ready. The DO will enter the high-impedance state on the falling edge of the CS.

2.1 Start Condition

The Start bit is detected by the device if CS and DI are both high with respect to the positive edge of CLK for the first time.

Before a Start condition is detected, CS, CLK and DI may change in any combination (except to that of a Start condition), without resulting in any device operation (Read, Write, Erase, EWEN, EWDS, ERAL and WRAL). As soon as CS is high, the device is no longer in the Standby mode.

An instruction following a Start condition will only be executed if the required amount of opcode, address and data bits for any particular instruction are clocked in.

After execution of an instruction (i.e., clock in or out of the last required address or data bit) CLK and DI become “don't care” bits until a new Start condition is detected.

2.2 DI/DO

It is possible to connect the Data In and Data Out pins together. However, with this configuration it is possible for a “bus conflict” to occur during the “dummy zero” that precedes the read operation, if A0 is a logic high level. Under such a condition the voltage level seen at Data Out is undefined and will depend upon the relative impedances of Data Out and the signal source driving A0. The higher the current sourcing capability of A0, the higher the voltage at the Data Out pin.

2.3 Erase/Write Enable and Disable (EWEN, EWDS)

The 93LC76/86 powers up in the Erase/Write Disable (EWDS) state. All programming modes must be preceded by an Erase/Write Enable (EWEN) instruction. Once the EWEN instruction is executed, programming remains enabled until an EWDS instruction is executed or Vcc is removed from the device. To protect against accidental data disturb, the EWDS instruction can be used to disable all erase/write functions and should follow all programming operations. Execution of a READ instruction is independent of both the EWEN and EWDS instructions.

2.4 Data Protection

During power-up, all programming modes of operation are inhibited until Vcc has reached a level greater than 1.4V. During power-down, the source data protection circuitry acts to inhibit all programming modes when Vcc has fallen below 1.4V.

The EWEN and EWDS commands give additional protection against accidentally programming during normal operation.

After power-up, the device is automatically in the EWDS mode. Therefore, an EWEN instruction must be performed before any ERASE or WRITE instruction can be executed.

3.0 DEVICE OPERATION

3.1 READ

The **READ** instruction outputs the serial data of the addressed memory location on the DO pin. A dummy zero bit precedes the 16-bit (x16 organization) or 8-bit (x8 organization) output string. The output data bits will toggle on the rising edge of the CLK and are stable after the specified time delay (T_{PD}). Sequential read is possible when CS is held high and clock transitions continue. The memory Address Pointer will automatically increment and output data sequentially.

3.2 ERASE

The **ERASE** instruction forces all data bits of the specified address to the logical "1" state. The self-timed programming cycle is initiated on the rising edge of CLK as the last address bit (A0) is clocked in. At this point, the CLK, CS and DI inputs become "don't cares".

The DO pin indicates the Ready/Busy status of the device if the CS is high. The Ready/Busy status will be displayed on the DO pin until the next Start bit is received as long as CS is high. Bringing the CS low will place the device in Standby mode and cause the DO pin to enter the high-impedance state. DO at logical "0" indicates that programming is still in progress. DO at logical "1" indicates that the register at the specified address has been erased and the device is ready for another instruction.

The erase cycle takes 3 ms per word (typical).

3.3 WRITE

The **WRITE** instruction is followed by 16 bits (or by 8 bits) of data to be written into the specified address. The self-timed programming cycle is initiated on the rising edge of CLK as the last data bit (D0) is clocked in. At this point, the CLK, CS and DI inputs become "don't cares".

The DO pin indicates the Ready/Busy status of the device if the CS is high. The Ready/Busy status will be displayed on the DO pin until the next Start bit is received as long as CS is high. Bringing the CS low will place the device in Standby mode and cause the DO pin to enter the high-impedance state. DO at logical "0" indicates that programming is still in progress. DO at logical "1" indicates that the register at the specified address has been written and the device is ready for another instruction.

The write cycle takes 3 ms per word (typical).

3.4 Erase All (ERAL)

The **ERAL** instruction will erase the entire memory array to the logical "1" state. The ERAL cycle is identical to the erase cycle except for the different opcode. The ERAL cycle is completely self-timed and commences on the rising edge of the last address bit (A0). Note that the Least Significant 8 or 9 address bits are "don't care" bits, depending on selection of x16 or x8 mode. Clocking of the CLK pin is not necessary after the device has entered the self clocking mode. The **ERAL** instruction is ensured at $V_{CC} = +4.5V$ to $+6.0V$.

The DO pin indicates the Ready/Busy status of the device if the CS is high. The Ready/Busy status will be displayed on the DO pin until the next Start bit is received as long as CS is high. Bringing the CS low will place the device in Standby mode and cause the DO pin to enter the high-impedance state. DO at logical "0" indicates that programming is still in progress. DO at logical "1" indicates that the entire device has been erased and is ready for another instruction.

The ERAL cycle takes 15 ms maximum (8 ms typical).

3.5 Write All (WRAL)

The **WRAL** instruction will write the entire memory array with the data specified in the command. The WRAL cycle is completely self-timed and commences on the rising edge of the last address bit (A0). Note that the Least Significant 8 or 9 address bits are "don't cares", depending on selection of x16 or x8 mode. Clocking of the CLK pin is not necessary after the device has entered the self clocking mode. The WRAL command does include an automatic ERAL cycle for the device. Therefore, the WRAL instruction does not require an ERAL instruction but the chip must be in the EWEN status. The WRAL instruction is ensured at $V_{CC} = +4.5V$ to $+6.0V$.

The DO pin indicates the Ready/Busy status of the device if the CS is high. The Ready/Busy status will be displayed on the DO pin until the next Start bit is received as long as CS is high. Bringing the CS low will place the device in Standby mode and cause the DO pin to enter the high-impedance state. DO at logical "0" indicates that programming is still in progress. DO at logical "1" indicates that the entire device has been written and is ready for another instruction.

The WRAL cycle takes 30 ms maximum (16 ms typical).

93LC76/86

FIGURE 3-1: SYNCHRONOUS DATA TIMING

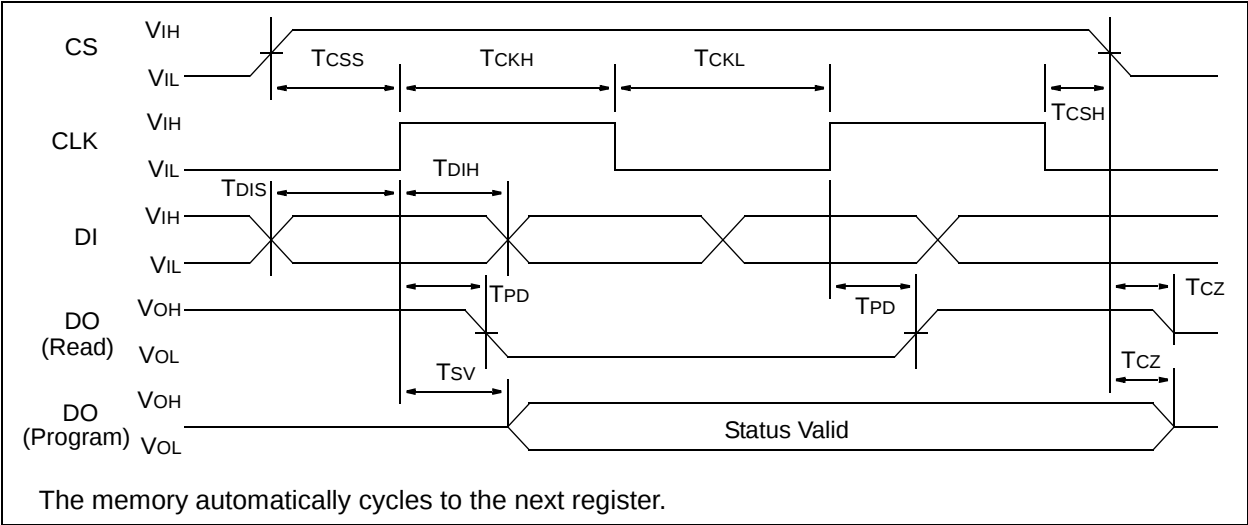


FIGURE 3-2: READ

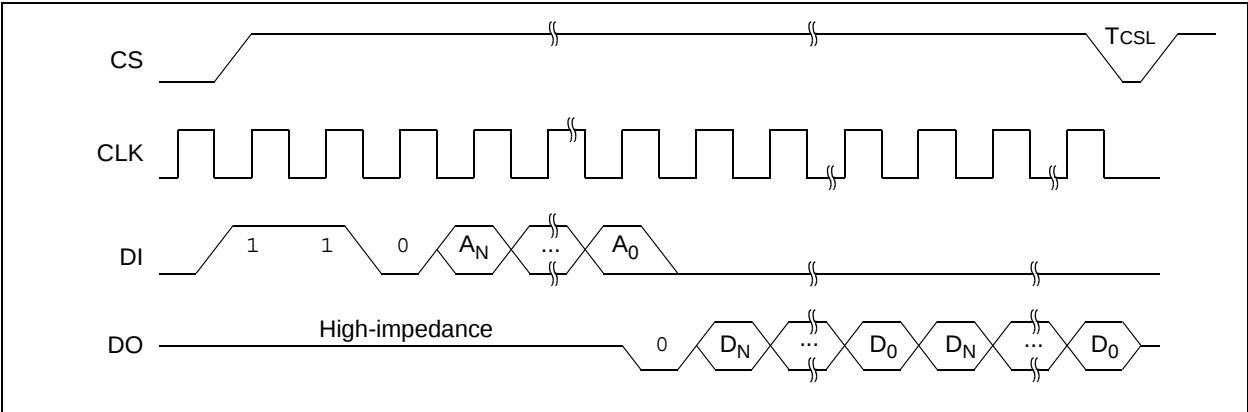


FIGURE 3-3: EWEN

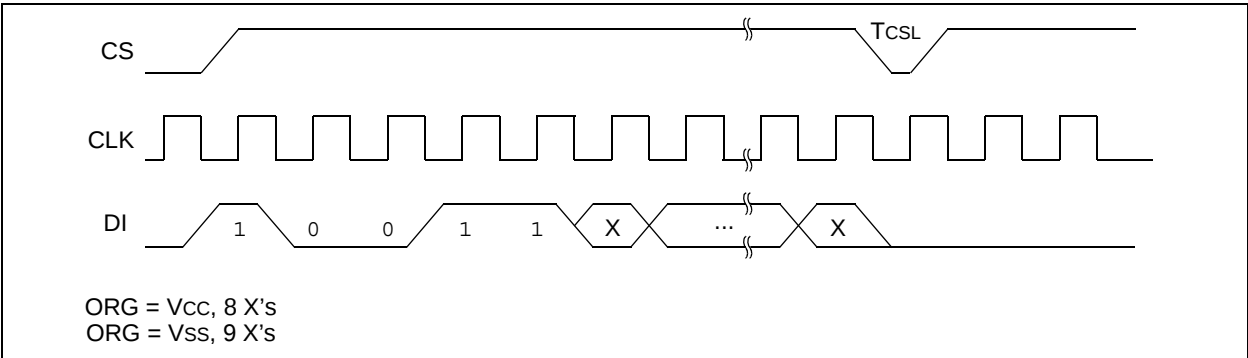


FIGURE 3-4: EWDS

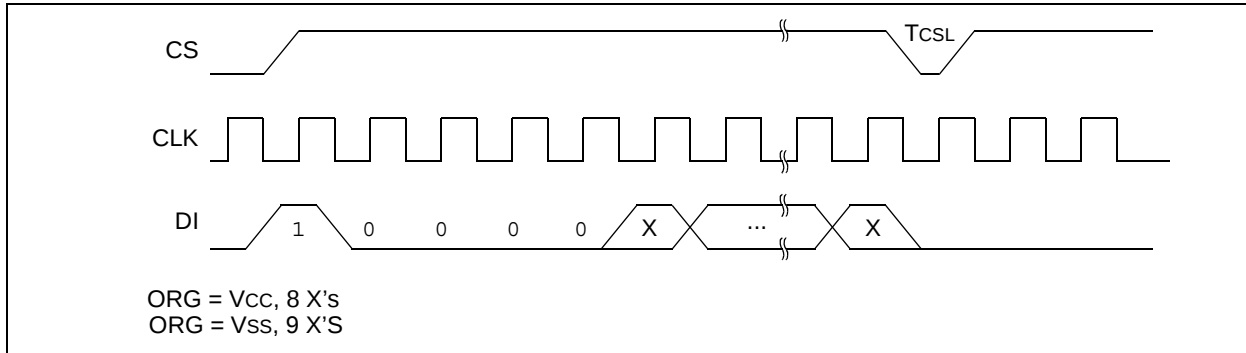


FIGURE 3-5: WRITE

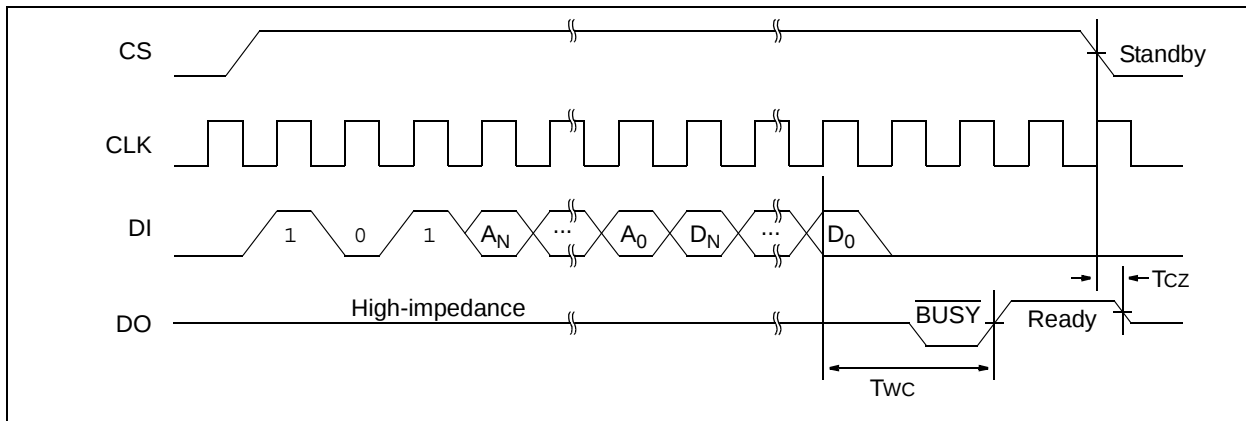


FIGURE 3-6: WRAL

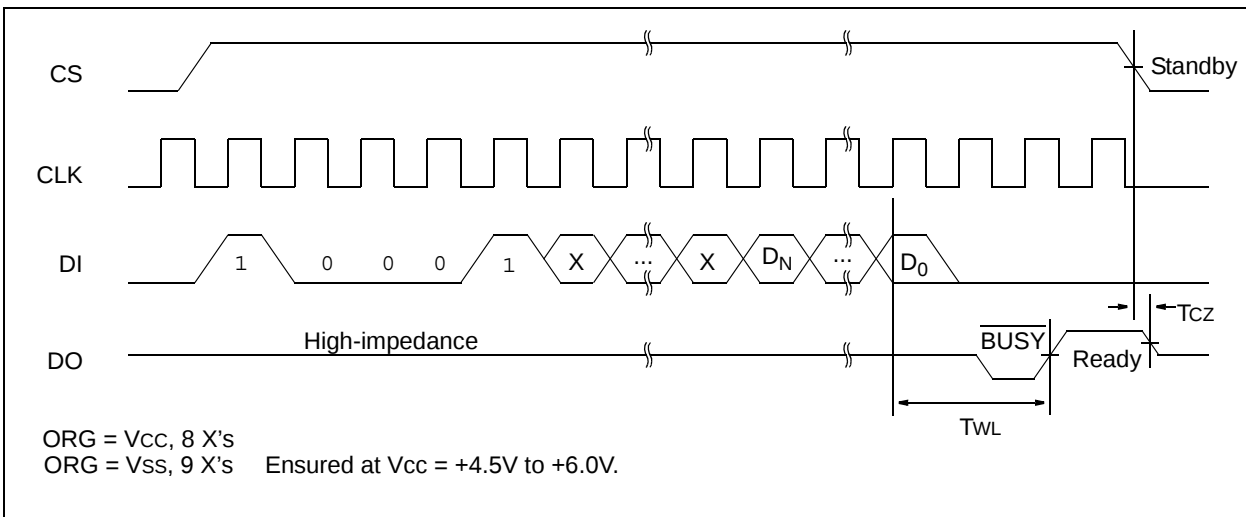


FIGURE 3-7: ERASE

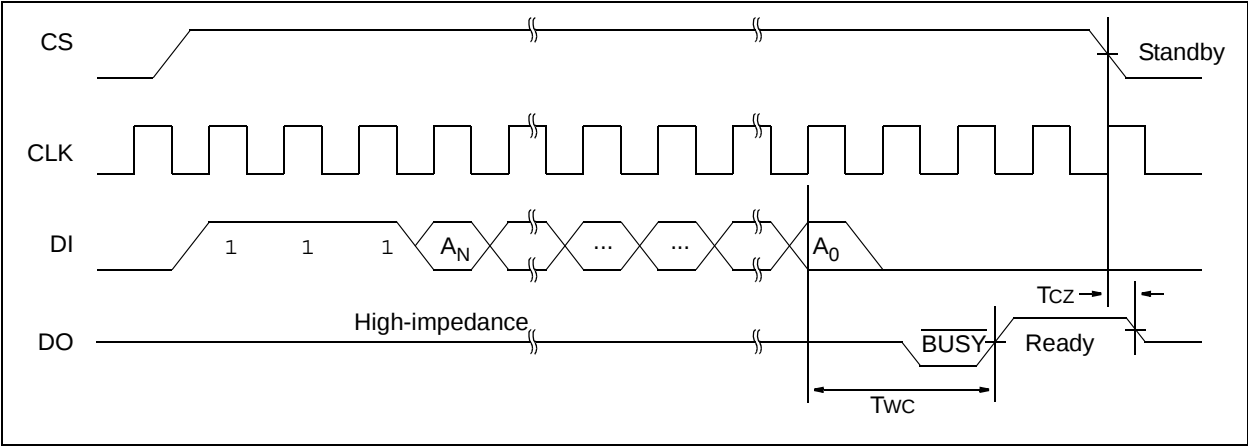
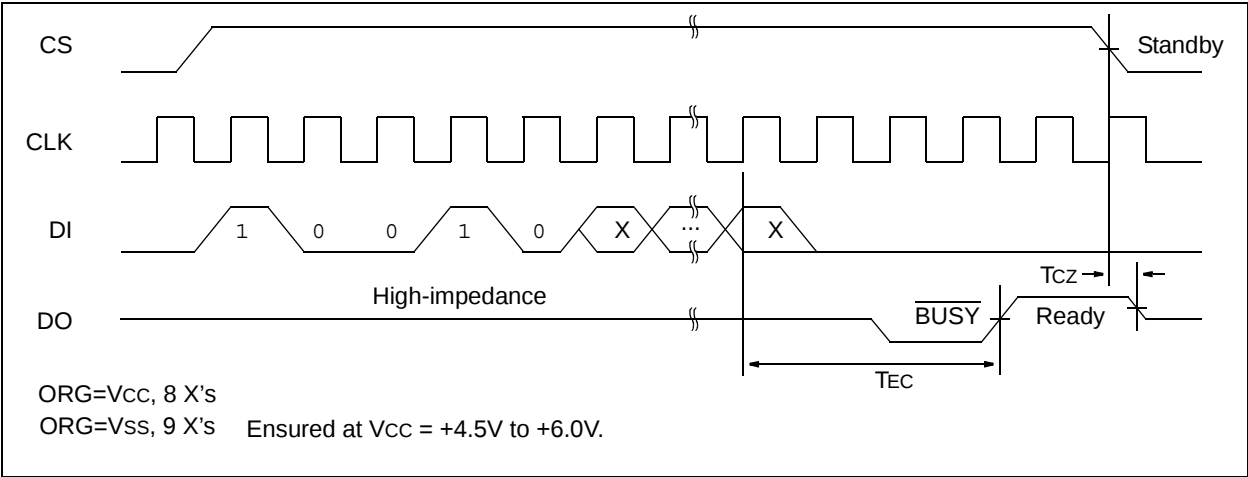


FIGURE 3-8: ERAL



4.0 PIN DESCRIPTIONS

TABLE 4-1: PIN FUNCTION TABLE

Name	Function
CS	Chip Select
CLK	Serial Data Clock
DI	Serial Data Input
DO	Serial Data Output
Vss	Ground
ORG	Memory Configuration
PE	Program Enable
Vcc	Power Supply

4.1 Chip Select (CS)

A high level selects the device. A low level deselects the device and forces it into Standby mode. However, a programming cycle which is already initiated will be completed, regardless of the CS input signal. If CS is brought low during a program cycle, the device will go into Standby mode as soon as the programming cycle is completed.

CS must be low for 250 ns minimum (T_{CSL}) between consecutive instructions. If CS is low, the internal control logic is held in a Reset status.

4.2 Serial Clock (CLK)

The Serial Clock is used to synchronize the communication between a master device and the 93LC76/86. Opcode, address and data bits are clocked in on the positive edge of CLK. Data bits are also clocked out on the positive edge of CLK.

CLK can be stopped anywhere in the transmission sequence (at high or low level) and can be continued anytime with respect to clock high time (T_{CKH}) and clock low time (T_{CKL}). This gives the controlling master freedom in preparing opcode, address and data.

CLK is a "don't care" if CS is low (device deselected). If CS is high, but Start condition has not been detected, any number of clock cycles can be received by the device without changing its status (i.e., waiting for Start condition).

CLK cycles are not required during the self-timed WRITE (i.e., auto erase/write) cycle.

After detection of a Start condition the specified number of clock cycles (respectively low-to-high transitions of CLK) must be provided. These clock cycles are required to clock in all opcode, address, and data bits before an instruction is executed (see Table 1-3 through Table 1-6 for more details). CLK and DI then become "don't care" inputs waiting for a new Start condition to be detected.

Note: CS must go low between consecutive instructions, except when performing a sequential read (Refer to **Section 3.1 "READ"** for more detail on sequential reads).

4.3 Data In (DI)

Data In is used to clock in a Start bit, opcode, address and data synchronously with the CLK input.

4.4 Data Out (DO)

Data Out is used in the Read mode to output data synchronously with the CLK input (T_{PD} after the positive edge of CLK).

This pin also provides Ready/Busy status information during erase and write cycles. Ready/Busy status information is available when CS is high. It will be displayed until the next Start bit occurs as long as CS stays high.

4.5 Organization (ORG)

When ORG is connected to Vcc, the x16 memory organization is selected. When ORG is tied to Vss, the x8 memory organization is selected. There is an internal pull-up resistor on the ORG pin that will select x16 organization when left unconnected.

4.6 Program Enable (PE)

This pin allows the user to enable or disable the ability to write data to the memory array. If the PE pin is floated or tied to Vcc, the device can be programmed. If the PE pin is tied to Vss, programming will be inhibited. There is an internal pull-up on this device that enables programming if this pin is left floating.

93LC76/86

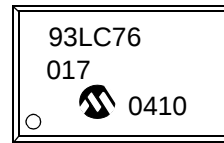
5.0 PACKAGING INFORMATION

5.1 Package Marking Information

8-Lead PDIP



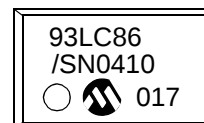
Example



8-Lead SOIC (.150")

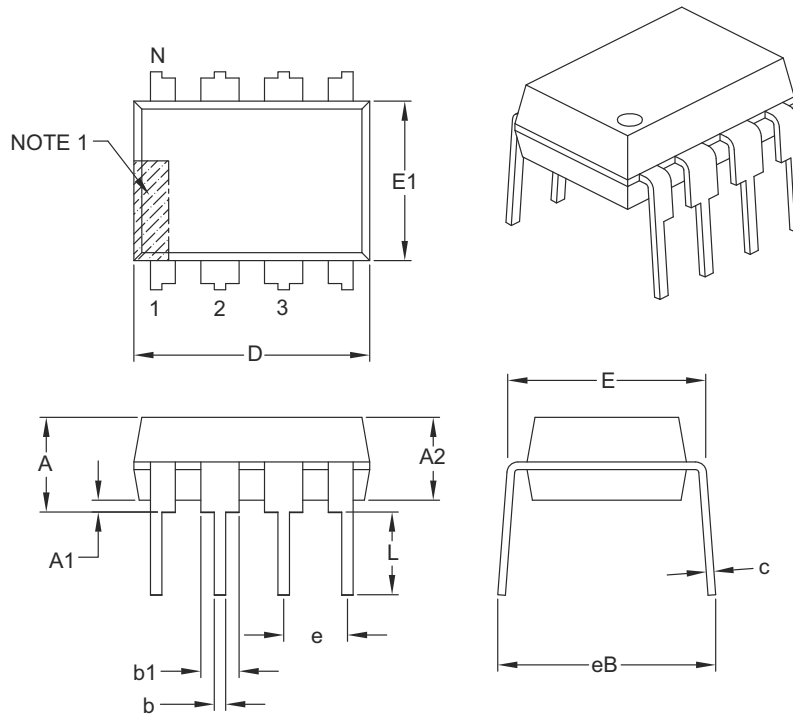


Example



8-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.348	.365	.400
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

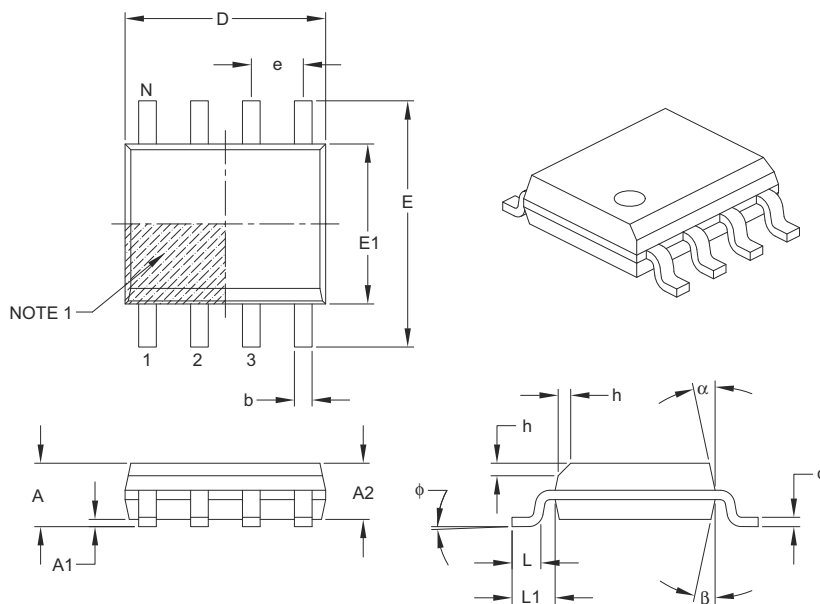
Notes:

- Pin 1 visual index feature may vary, but must be located with the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-018B

8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		8		
Pitch	e		1.27 BSC		
Overall Height	A		–	–	1.75
Molded Package Thickness	A2		1.25	–	–
Standoff §	A1		0.10	–	0.25
Overall Width	E		6.00 BSC		
Molded Package Width	E1		3.90 BSC		
Overall Length	D		4.90 BSC		
Chamfer (optional)	h		0.25	–	0.50
Foot Length	L		0.40	–	1.27
Footprint	L1		1.04 REF		
Foot Angle	φ		0°	–	8°
Lead Thickness	c		0.17	–	0.25
Lead Width	b		0.31	–	0.51
Mold Draft Angle Top	α		5°	–	15°
Mold Draft Angle Bottom	β		5°	–	15°

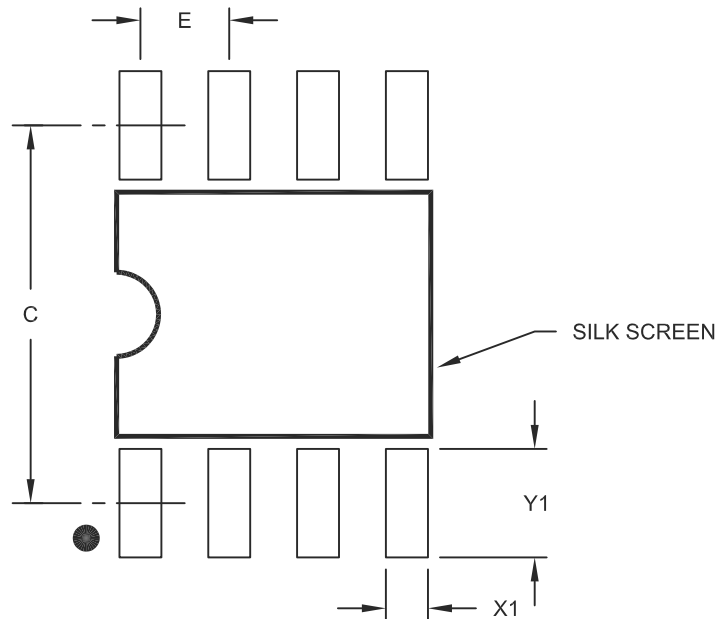
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-057B

8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units	Dimension Limits	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A

APPENDIX A: REVISION HISTORY

Revision E

Added note to page 1 header (Not recommended for new designs).

Added Section 5.0: Package Marking Information.

Added On-line Support page.

Updated document format.

Revision F

Removed Preliminary Status.

ON-LINE SUPPORT

Microchip provides on-line support on the Microchip World Wide Web site.

The web site is used by Microchip as a means to make files and information easily available to customers. To view the site, the user must have access to the Internet and a web browser, such as Netscape® or Microsoft® Internet Explorer. Files are also available for FTP download from our FTP site.

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www.microchip.com

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- Latest Microchip Press Releases
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- Design Tips
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Device: 93LC76/86

Literature Number: DS21131F

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PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>		<u>X</u>	<u>/XX</u>	<u>XXX</u>
Device		Temperature Range	Package	Pattern
Device 93LC76/86: Microwire Serial EEPROM 93LC76T/86T: Microwire Serial EEPROM (Tape and Reel)				
Temperature Range Blank = 0°C to +70°C I = -40°C to +85°C				
Package P = Plastic DIP (300 mil Body), 8-lead SN = Plastic SOIC (150 mil Body), 8-lead				

Sales and Support

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Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

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93LC76/86

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